

500 WATT LOW CAPACITANCE STEERING DIODE/TVS ARRAY



DESCRIPTION

The SR12 is a low capacitance steering diode TVS array, designed to protect two I/O lines from the effects of Electrostatic Discharge (ESD) and Electrical Fast Transients (EFT). The SR12 provides ESD protection and has a peak pulse power rating of 500 Watts for an 8/20 μ s waveshape.

The low capacitance of the steering diode allows the designer to protect high speed data applications. The small SOT-143 package, with four leads reduces the internal lead inductance for low overshoot voltage during fast front time transient events, such as ESD. The SR12 meets the IEC 61000-4-2 and IEC 61000-4-4 requirements.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air - 15kV, Contact - 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A - 5/50ns
- Compatible with IEC 61000-4-5 (Surge): 24A, 8/20 μ s - Level 2 (Line-Gnd) & Level 3 (Line-Line)
- 500 Watts Peak Pulse Power per Line ($t_p = 8/20\mu$ s)
- Protects Two I/O Ports & Power Supply
- Low Capacitance: 10pF
- RoHS Compliant
- REACH Compliant

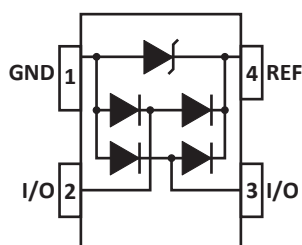
APPLICATIONS

- Ethernet - 10/100/1000 Base T
- USB
- Wireless Communications
- FireWire

MECHANICAL CHARACTERISTICS

- Molded JEDEC SOT-143 Package
- Approximate Weight: 9 milligrams
- Lead-Free Pure-Tin Plating (Annealed)
- Solder Reflow Temperature:
Pure-Tin - Sn, 100: 260-270°C
- 8mm Tape and Reel Per EIA Standard 481
- Flammability Rating UL 94V-0

PIN CONFIGURATION



TYPICAL DEVICE CHARACTERISTICS
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Operating Temperature	T_L	-55 to 150	°C
Storage Temperature	T_{STG}	-55 to 150	°C
Peak Pulse Power (tp = 8/20µs) - See Figure 1	P_{PP}	500	Watts
Peak Forward Voltage - $I_F = 1A$, 8/20µs	V_F	1.5	Volts

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER	DEVICE MARKING	RATED STAND-OFF VOLTAGE V_{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA $V_{(BR)}$ VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ $I_P = 1A$ V_C VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ 8/20µs $V_C @ I_{PP}$ VOLTS	MAXIMUM LEAKAGE CURRENT @ V_{WM} I_D µA	MAXIMUM CAPACITANCE PER LINE (Note 1) (Fig. 5) 0V, 1MHz $C_{J(SD)}$ pF
SR12	12A	12.0	13.3	19.0	30.0V @ 16.0A	1	10

NOTES

- As shown in Figure 5, REF 1 is connected to ground, REF 2 is connected to + V_{CC} and input applies to $V_{CC} = 12V$, $V_{SIGN} = 30mV$, $F = 1MHz$.

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

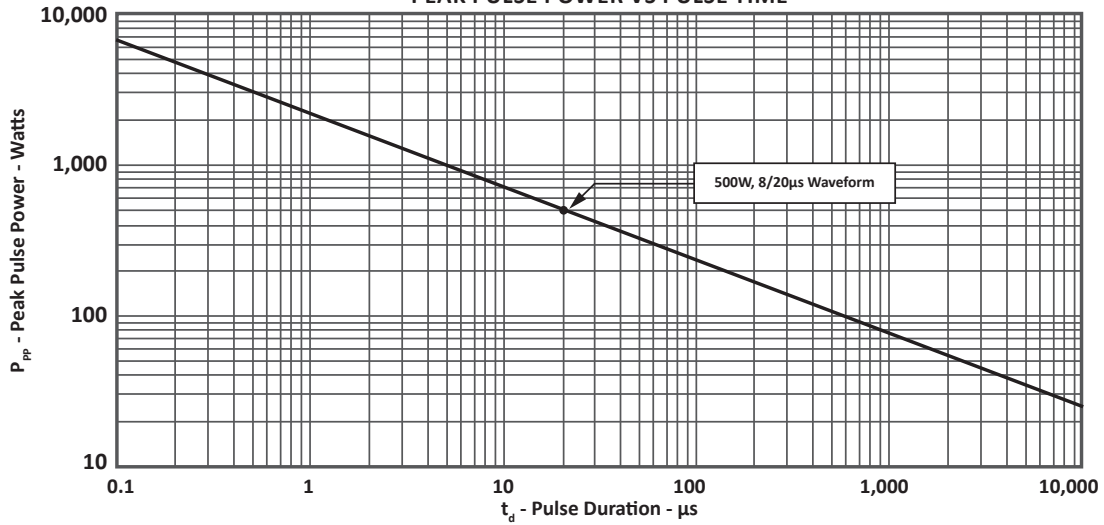


FIGURE 2
PULSE WAVE FORM

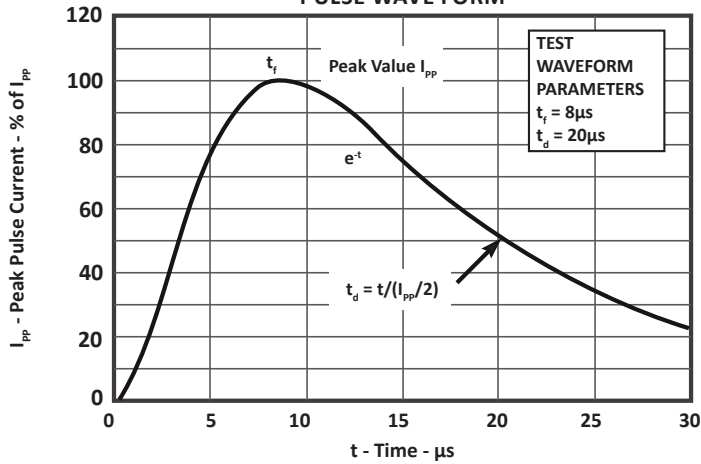
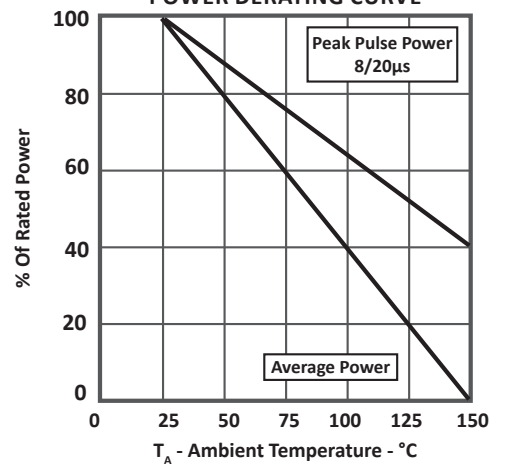


FIGURE 3
POWER DERATING CURVE



TYPICAL DEVICE CHARACTERISTICS

FIGURE 4
OVERSHOOT & CLAMPING VOLTAGE

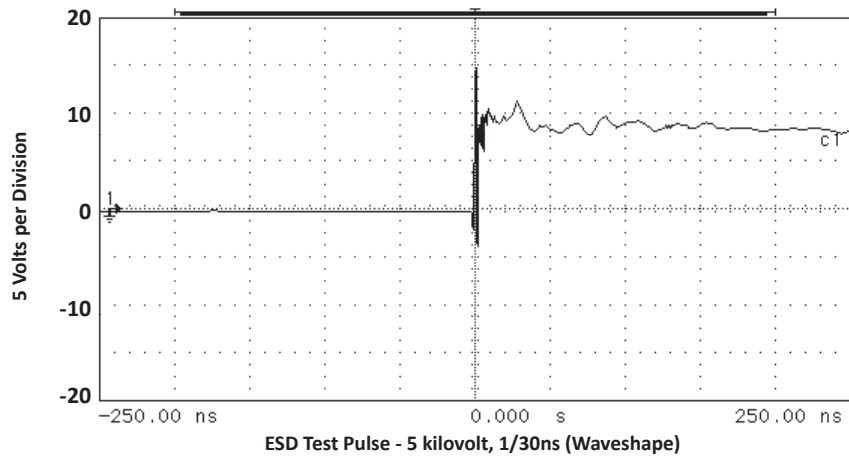


FIGURE 5
INPUT CAPACITANCE CIRCUIT

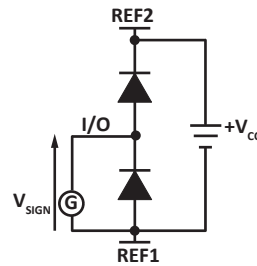
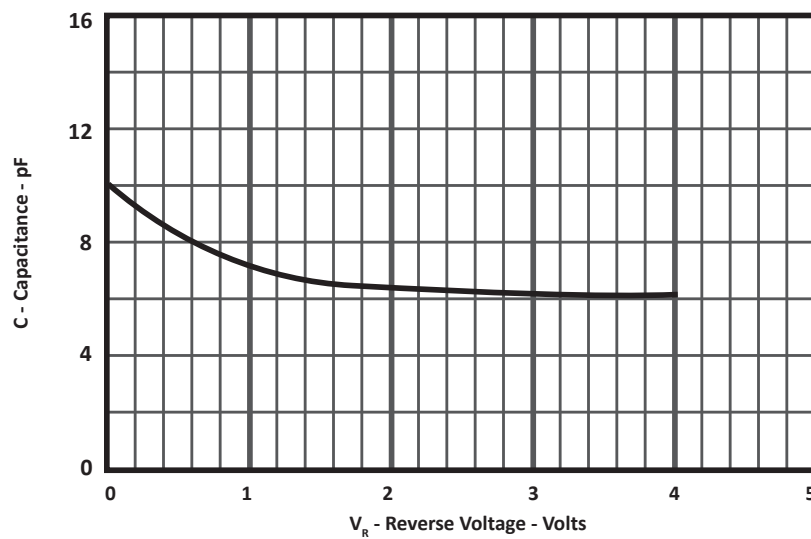


FIGURE 6
TYPICAL REVERSE VOLTAGE VS CAPACITANCE



APPLICATION INFORMATION

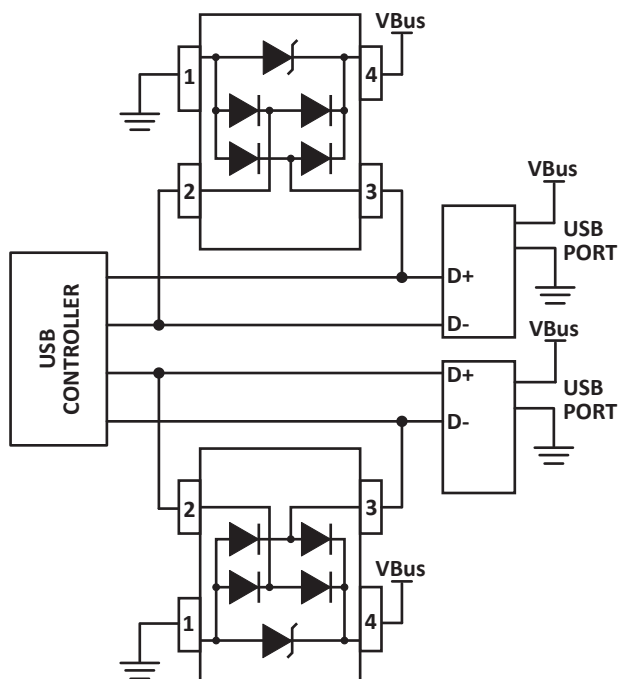


FIGURE 1 - USB PROTECTION

Two SR12s (Unidirectional) in a Common-Mode configuration. Circuit connectivity is as follows:

- Pins 2 and 3 are connected to the datalines
- Pin 1 is connected to ground
- Pin 4 is connected to the databus

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

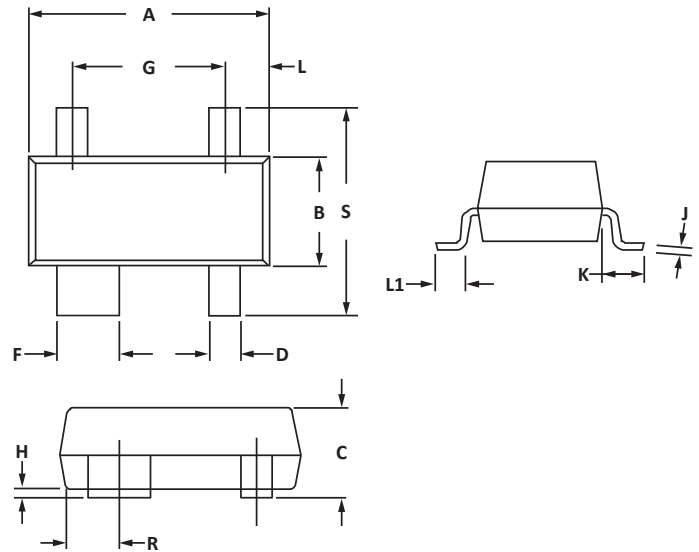
- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

SOT-143 PACKAGE INFORMATION
OUTLINE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.80	3.04	0.110	0.120
B	1.20	1.39	0.047	0.055
C	0.84	1.14	0.033	0.045
D	0.39	0.50	0.015	0.020
F	0.79	0.93	0.031	0.037
G	1.78	2.03	0.070	0.080
J	0.08	0.15	0.003	0.006
K	0.46	0.60	0.018	0.024
L	0.445	0.60	0.0175	0.024
L1	0.40	0.60	0.016	0.024
R	0.72	0.83	0.028	0.033
S	2.11	2.48	0.083	0.098

NOTES

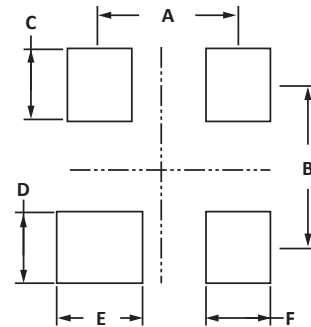
1. Dimensioning and tolerances per ANSI Y14.M, 1985.
2. Controlling dimension: inches.
3. Dimensions are exclusive of mold flash and metal burrs.


PAD LAYOUT DIMENSIONS

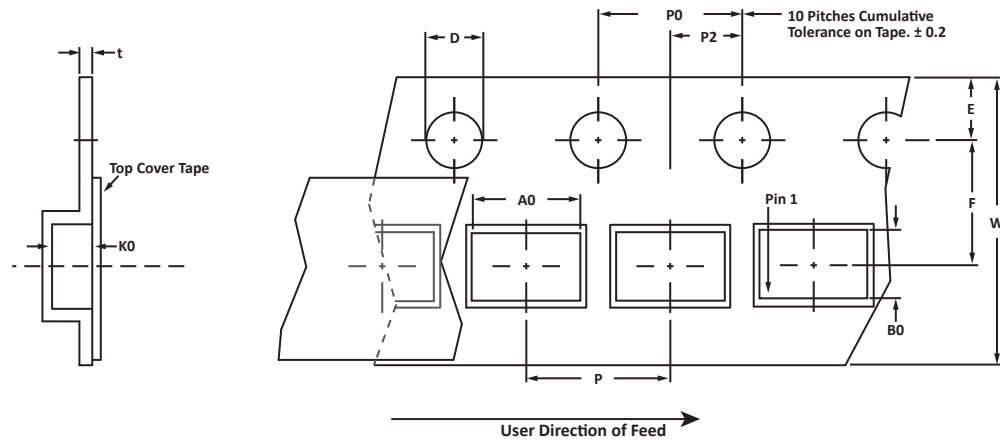
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.88	2.13	0.074	0.084
B	1.80	2.06	0.071	0.081
C	0.71	0.97	0.028	0.038
D	0.76	1.02	0.030	0.040
E	1.07	1.32	0.042	0.052
F	0.71	0.97	0.028	0.038

NOTES

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	3.10 ± 0.10	2.70 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES

1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 3,000 pieces per 8mm tape.
4. Suffix - T13 = 13" Reel - 10,000 pieces per 8mm tape.
5. Marking on Part - marking code (see page 2) and date code.

Package outline, pad layout and tape specifications per document number 06011.R4 8/10.

ORDERING INFORMATION

BASE PART NUMBER	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
SR12	-LF	-T7	3000	7"	n/a
SR12	-LF	-T13	10,000	13"	n/a

This device is only available in a Lead-Free configuration.

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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